



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





MID-PERFORMANCE GAP FILLER WITH 1.8 W/MK

Tflex™ HR400 is a cost-effective and compliant gap filler thermal interface material with excellent thermal performance and great handling for mass-production applications.

The low modulus interface pad conforms to component topography, resulting in little stress on the components, mating chassis or parts. The softness relieves mechanical stress from high stack-up tolerance and absorbs shock, resulting in improved device reliability. Tflex™ HR400's recovery properties for applications requiring material rework result in continued mechanical integrity even after device rework and re-assembly.

Tflex™ HR400 is naturally tacky on both sides and requires no additional adhesive coating to inhibit thermal performance. The tack is designed to hold the pad in place during assembly and component transport.

Tflex™ HR400 is electrically insulating, stable from -50°C thru 160°C, and meets UL 94V0 flame rating.

FEATURES AND BENEFITS

- Thermal Conductivity 1.8 W/mK
- Soft and Compliant
- Available in thicknesses from 0.020" thru 0.400" (0.5mm thru 10.2mm)
- Naturally tacky for adhesion during assembly and transport

APPLICATIONS

- Cooling components to chassis, frame, or other mating components
- Memory Modules
- Home and small office network equipment
- Mass storage devices
- Automotive electronics
- Telecommunication hardware
- Radios
- LED solid state lighting
- Power electronics
- LCD and PDP flat panel TV
- Set top boxes
- Audio and video components
- IT infrastructure
- GPS navigation and other portable devices

global solutions: local support.™

Americas: +1.800.843.4556

Europe: +49.8031.2460.0

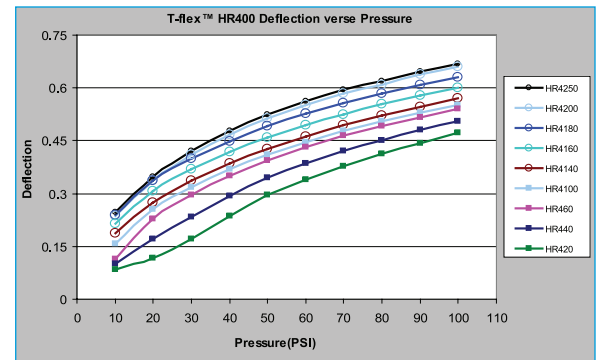
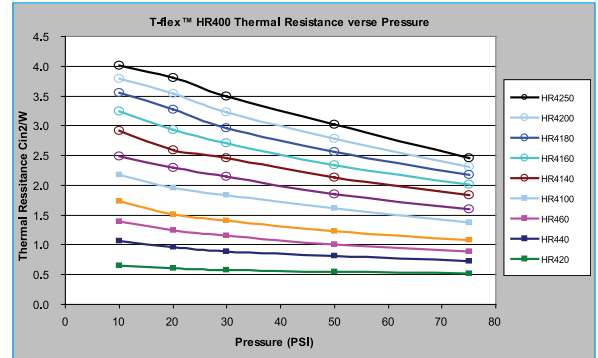
Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

Tflex™ HR400 TYPICAL PROPERTIES

	Tflex HR400™	TEST METHOD
Construction	Ceramic filled silicone elastomer	NA
Color	Dark Grey	Visual
Thermal Conductivity	1.8 W/mK	Hot Disk™
Hardness (Shore 00)	60	ASTM D2240
Specific Gravity	1.93	Helium Pycnometer
Thickness Range	0.020" - .400" (0.5 - 10.2mm)	
Thickness Tolerance	±10%	
UL Flammability Rating	94 V0	File E180840
Temperature Range	-50°C to 160°C	See reliability report
Outgassing TML	0.32%	ASTM E595
Outgassing CVM	0.09%	ASTM E595
Coefficient Thermal Expansion (CTE)	651 ppm/°C 35°C-108°C	IPC-TM-650 2.4.24



STANDARD THICKNESSES

Standard thickness is 0.020-inch (0.5 mm) through 0.400-inch (10.2 mm) and available in 0.010-inch increments. Please contact Laird Technologies for availability of thicknesses above 0.200-inch.

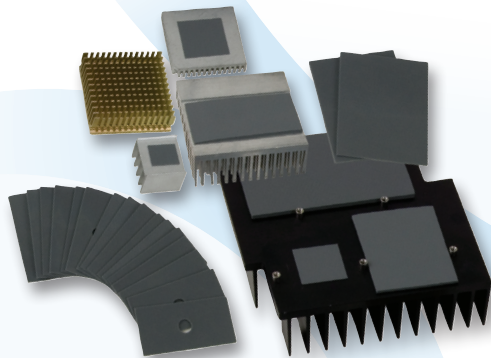
OPTIONS

Fiberglass is standard in 0.020-inch and 0.030-inch thicknesses to aid in handling and is designated by the suffix "-FG". Material is standard with both sides tacky; the -DC1 suffix indicates only one side is tacky.

MATERIAL NAME AND THICKNESS

Tflex™ indicates Laird Technologies' elastomeric thermal gap filler product line. HR4XXX indicates Tflex HR400 product line with thickness in mils (0.001-inches); -DC1 indicates only one side tacky; -FG indicates fiberglass reinforcement.

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.



THR-DS-Tflex-HR400 1109

Any information furnished by Laird Technologies and its agents is believed to be accurate and reliable. Responsibility for the use and application of Laird Technologies materials rests with the end user since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability, or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies domestic terms and conditions of sale in effect from time to time, a copy of which will be furnished upon request. Laird Technologies' products are sold pursuant to the Laird Technologies' domestic terms and conditions of sale in effect from time to time, a copy of which will be furnished upon request. Document A15958-00 Rev B, 11/2009.